



Product Change Notification / JAON-16AAOX023

Date:

27-Oct-2022

Product Category:

Switching Regulators

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4777 Final Notice: Qualification of UAT as an additional Cu Pillar bumping site for selected LX7220 and LX7219 device families available in 14L VQFN (2x3x1.0mm) package and selected Microsemi LX7180A device family available in 12L VQFN (2x2x1.0mm) package.

Affected CPNs:

[JAON-16AAOX023_Affected_CPN_10272022.pdf](#)

[JAON-16AAOX023_Affected_CPN_10272022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of UAT as an additional Cu Pillar bumping site for selected LX7220 and LX7219 device families available in 14L VQFN (2x3x1.0mm) package and selected Microsemi LX7180A device family available in 12L VQFN (2x2x1.0mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
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Cu Pillar Bumping location	Unisem Chengdu Co.,Ltd. (UNIC)	Unisem Chengdu Co.,Ltd. (UNIC)	Unisem Advance Tech (UAT)
Bump Material	CuSn	CuSn	CuSn
Bump Diameter	130um	130um	130um

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying UAT as an additional Cu pillar bumping site.

Change Implementation Status:In Progress

Estimated First Ship Date:November 26, 2022 (date code: 2248)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2021					>	October 2022					November 2022				
Workweek	3	3	3	3	3		4	4	4	4	4	4	4	4	4	4
	2	3	4	5	6		0	1	2	3	4	5	6	7	8	9
Initial PCN Issue Date			X													
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date														X		

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

August 19, 2021: Issued initial notification.

October 27, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 26, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-16AAOX023_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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JAON-16AAOX023 - CCB 4777 Initial Notice: Qualification of UAT as an additional Cu Pillar bumping site for selected Microsemi LX7220 and LX7219 device families available in 14L VQFN (2x3x1.0mm) package and selected Microsemi LX7180A device family available in 12L VQFN (2x2x1.0mm) package.

Affected Catalog Part Numbers (CPN)

LX7180A-01CLQ-TR

LX7180A-11CLQ-TR

LX7180A-21CLQ-TR

LX7180A-31CLQ-TR

LX7219-01ILQ-TR

LX7219-02ILQ-TR

LX7220-03ILQ-TR